

**ROCHESTER INSTITUTE OF TECHNOLOGY  
MICROELECTRONIC ENGINEERING**

# CMOS Integrated Circuit Test Results

**Dr. Lynn Fuller, Ellen Sedlack**

**Microelectronic Engineering  
Rochester Institute of Technology  
82 Lomb Memorial Drive  
Rochester, NY 14623-5604  
Tel (585) 475-2035  
Fax (585) 475-5041**

**Dr. Fuller's Webpage: <http://www.rit.edu/~lffeee>**

**Email: [Lynn.Fuller@rit.edu](mailto:Lynn.Fuller@rit.edu)**

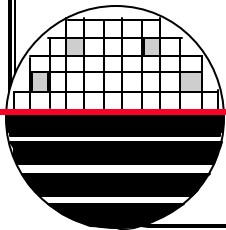
**Dept Webpage: <http://www.microe.rit.edu>**

*Rochester Institute of Technology  
Microelectronic Engineering*

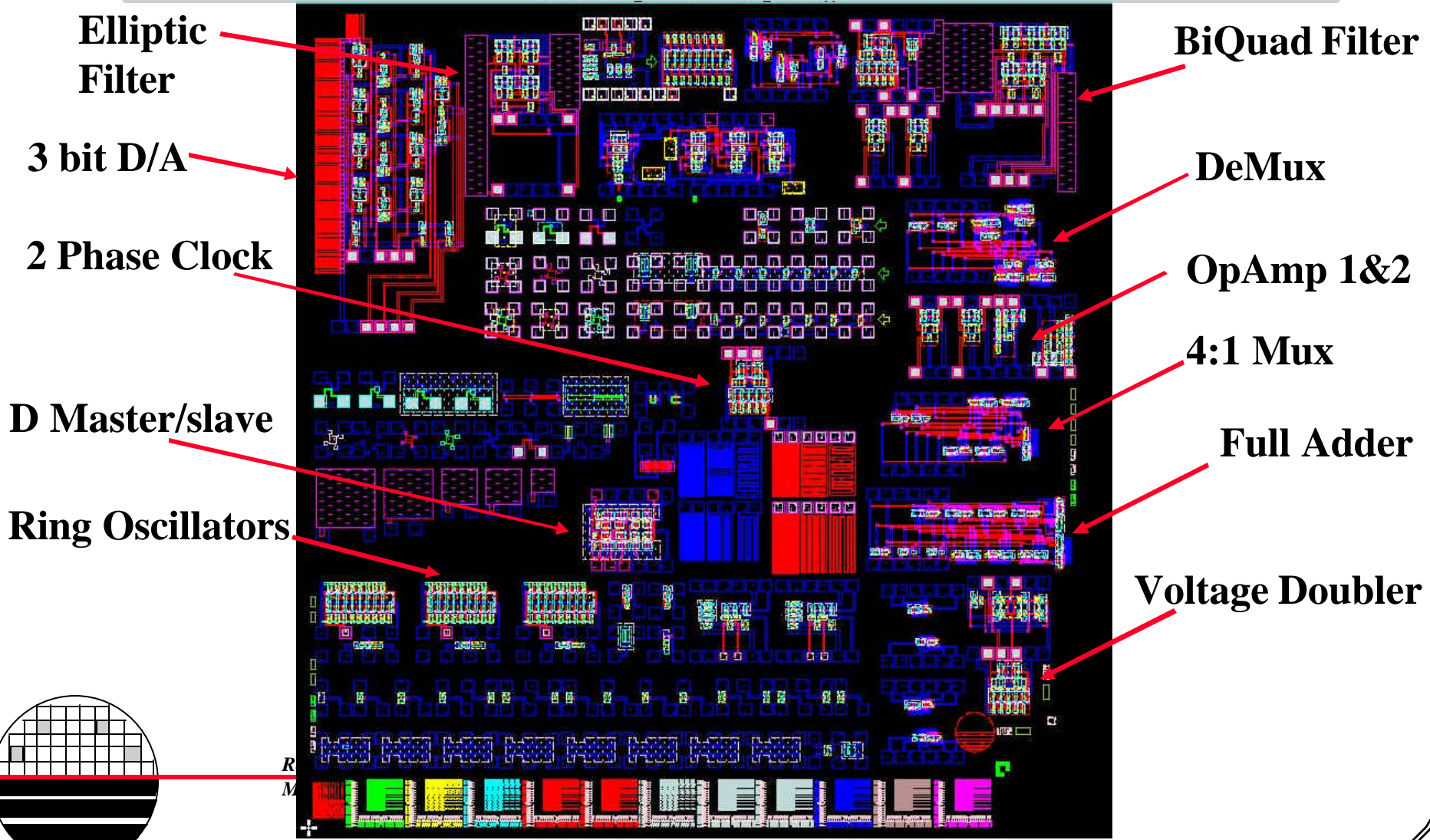
1-16-2009 CMOS\_IC\_Test.ppt

## OUTLINE

Layout  
Summary of Completed Factory Wafers  
Ring Oscillator  
Operational Amplifier  
Two Phase Non-Overlapping Clock  
2-Input NAND  
2-Input NOR  
3-Input NAND  
3-Input NOR  
Full Adder  
1 to 4 DeMUX  
4 to 1 MUX  
Voltage Doubler



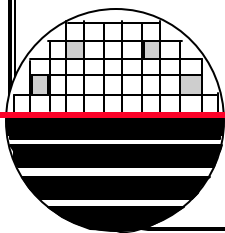
*MIXED ANALOG DIGITAL CMOS TESTCHIP*



**SUMMARY OF COMPLETED FACTORY WAFERS**

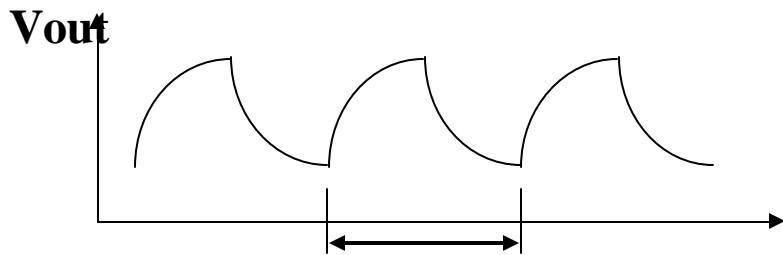
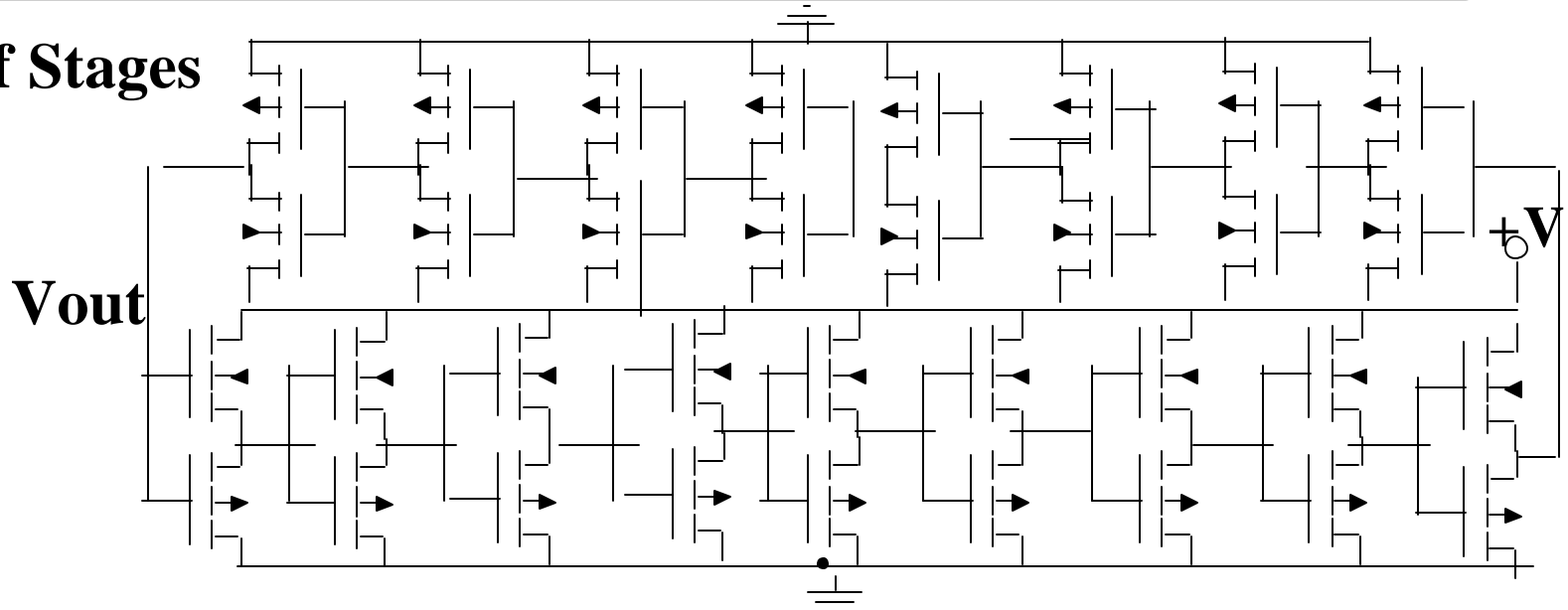
Lot No.	Product	Process	Wafer IDs	Vtn	Vtp	Comments
S030123	TESTCHIP	SUBCMOS				
S030922	MIXED	SUBCMOS	D2	2.6	None	suspect mask error for pmos
S030922	MIXED	SUBCMOS	D3	2	None	suspect mask error for pmos
S031013	MIXED	SUBCMOS	D2	1.26	None	suspect mask error for pmos
S040518	TESTCHIP	ADV				
S040318	TESTCHIP	ADV				
S040322	TESTCHIP	SMFL				
S040615	TESTCHIP	SMFL				
S040906	TESTCHIP	ADV				
S041004	MIXED	SUBCMOS	D1	0.7	-0.67	Metal Adhesion Poor
S050401	DAC	SMFL				
S050408	MIXED	SUBCMOS	D2	1.05	-0.89	
S050907	DAC	SMFL				
S051201	TESTCHIP	SMFL				
S051205	TESTCHIP	SMFL				
S070125	DAC	SMFL				
S070201	MIXED	SUBCMOS	D2	0.86	-0.88	
S070201	MIXED	SUBCMOS	D1	0.984	None	
S070208	TESTCHIP	SMFL				
S070910	MIXED	SUBCMOS	D1	0.4	-1.4	
S070910	MIXED	SUBCMOS	D3	0.6	-1.4	
S071001	MIXED	SUBCMOS	D1	0.94	-0.98	lot number not visible
S071001	MIXED	SUBCMOS	D2	0.76	-0.97	lot number not visible
S071001	MIXED	SUBCMOS	D3	1.82	None	lot number not visible

We tested all of the MIXED SUBCMOS lots that were completed in the last several years and found the NMOS and PMOS threshold voltages for the 2um transistors. Seven of the nine wafers completed had



**RING OSCILLATOR**

**Odd # of Stages**



**T = period of oscillation**

$$t_d = T/2N$$

**T = period of oscillation**

**N = number of stages**

**t<sub>d</sub> = gate delay**

***RING OSCILLATOR***

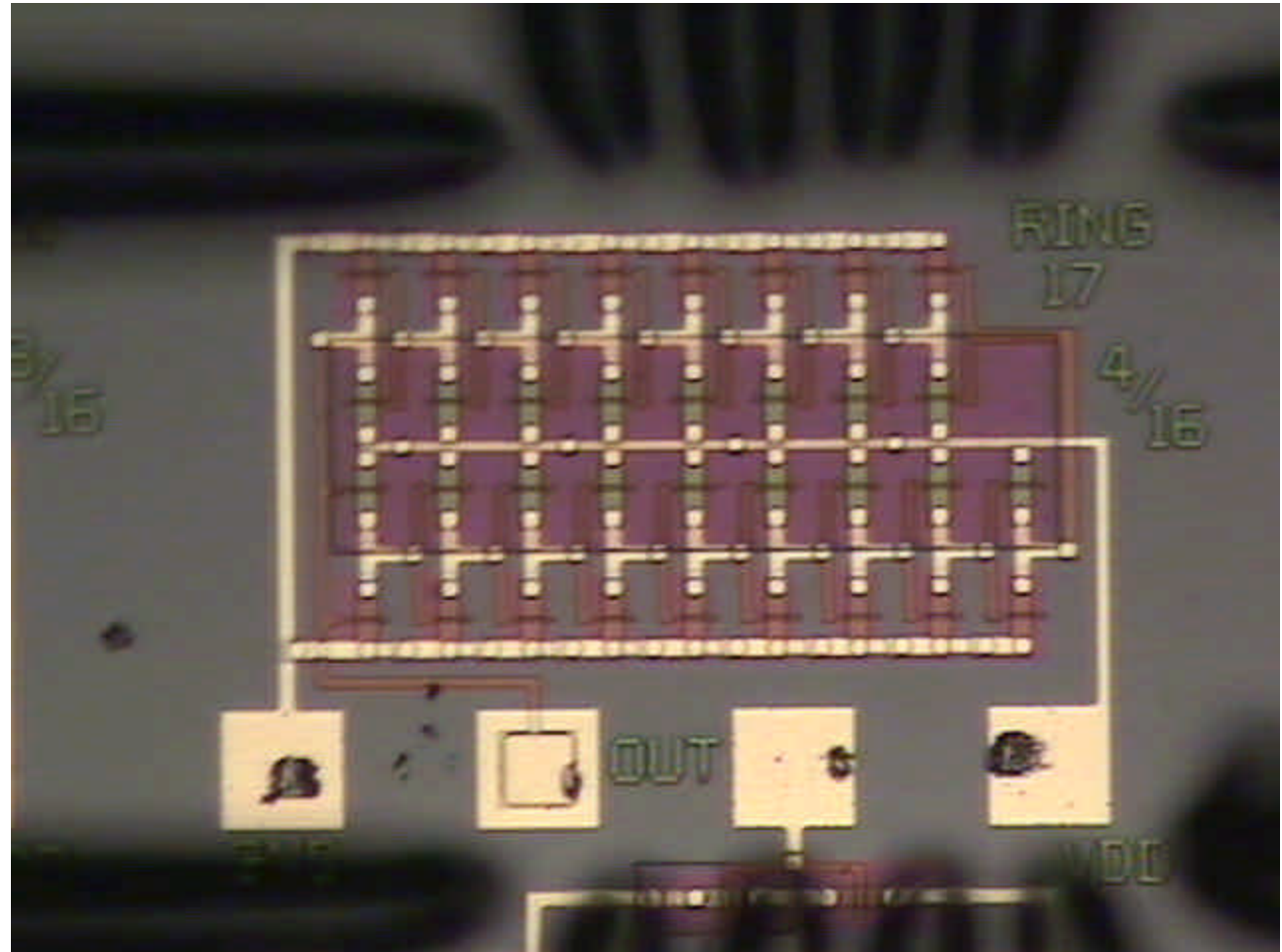
No buffer

17 Stage

L/W = 4/16

Vdd = 5V

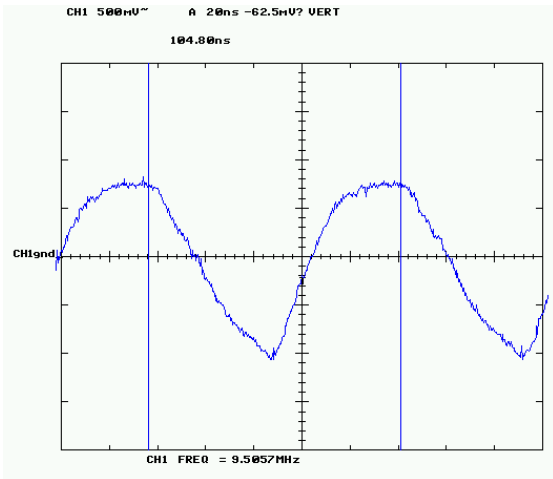
$$\begin{aligned} t_d &= \text{gate delay} \\ &= 90\text{ns}/2/17 \\ &= 2.6\text{ns} \end{aligned}$$



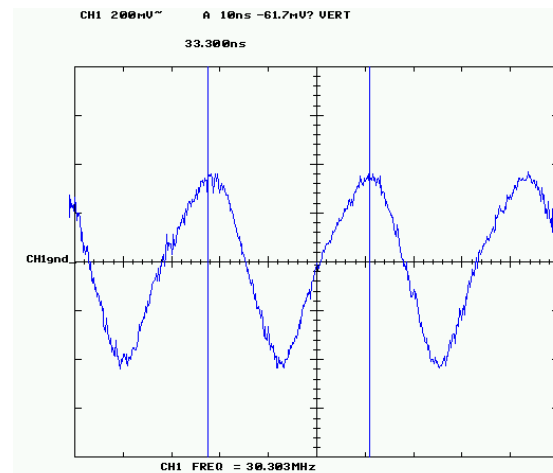
# RING OSCILLATOR

## SMFL CMOS Process

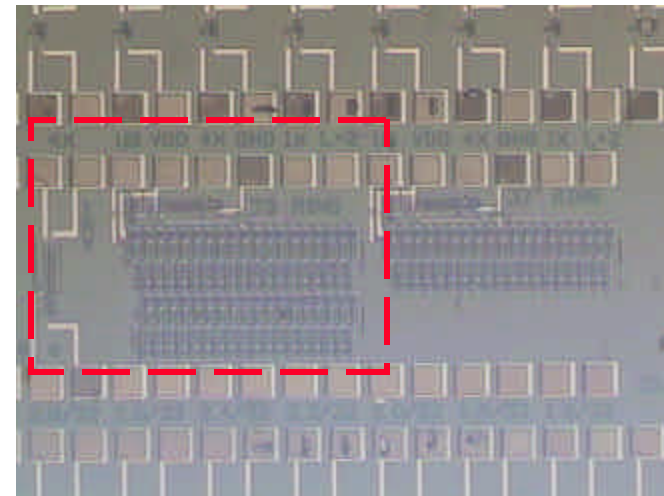
4x buffer



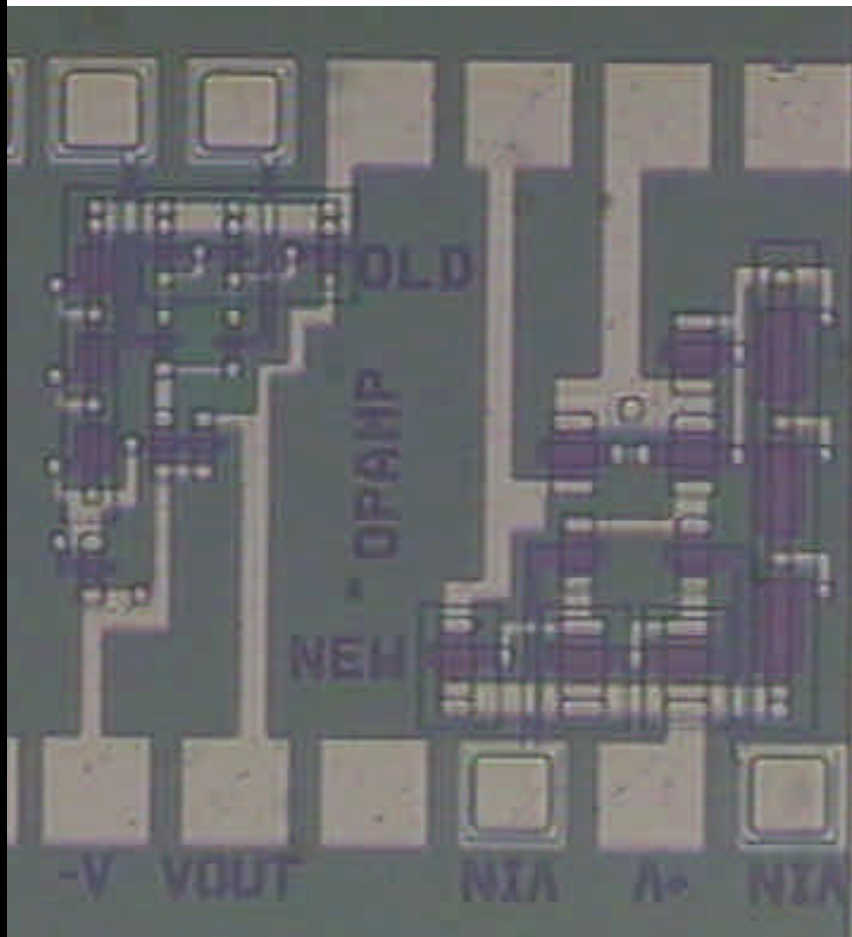
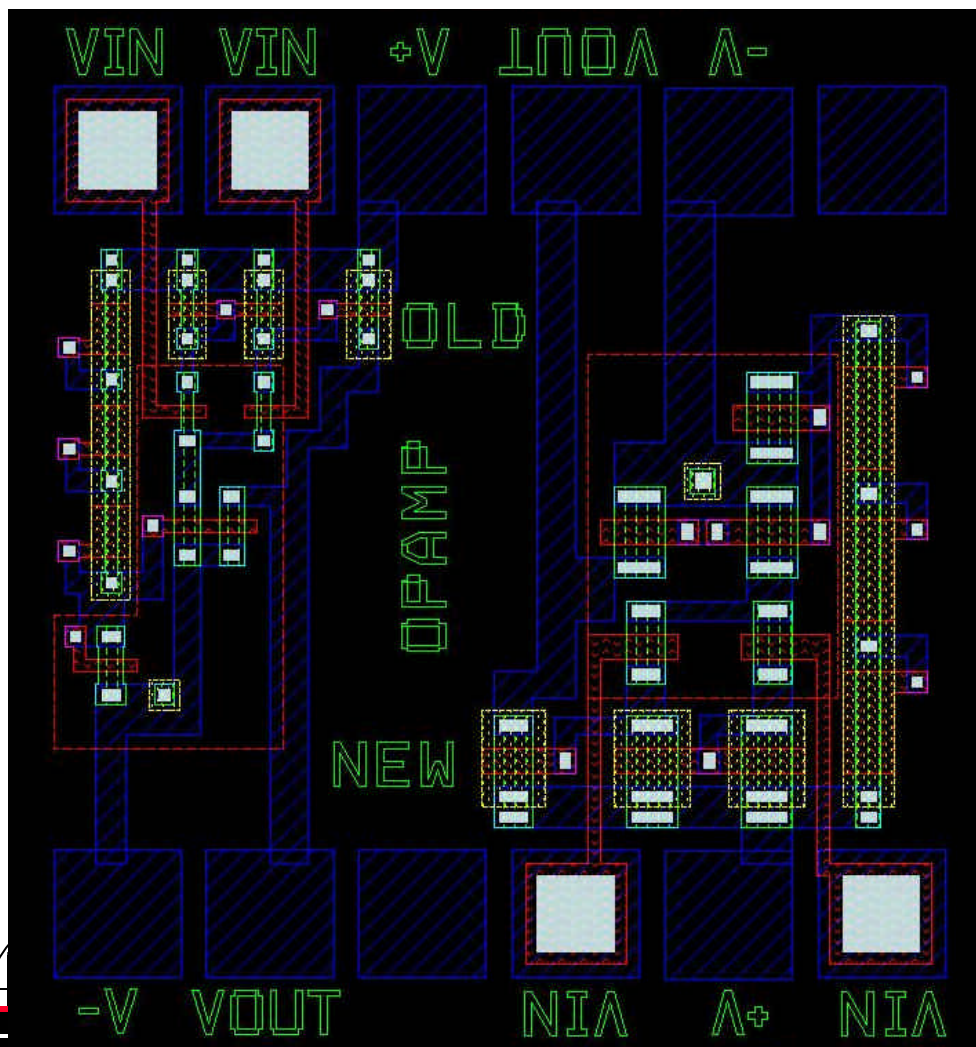
73 Stage Ring at 5V,  $t_d = 0.712\text{ns}$



73 Stage Ring at 6V,  $t_d = 0.228\text{ns}$

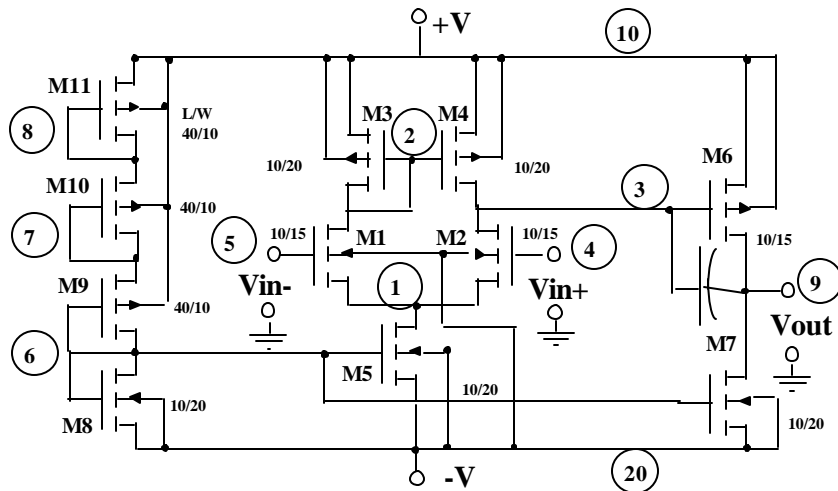


# OPERATIONAL AMPLIFIER





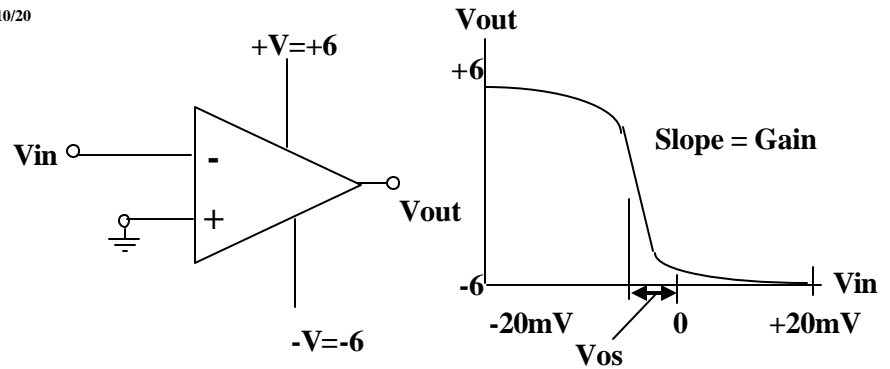
**OPERATIONAL AMPLIFIER**



p-well CMOS

dimensions  
L/W  
( $\mu\text{m}/\mu\text{m}$ )

Old Version Schematic  
New Version has L and W  
twice as large



Set up the HP 4145 to sweep the  $V_{in}$  from  $-20\text{ mV}$  to  $+20\text{ mV}$  in  $0.001\text{V}$  steps. Measure Gain and Input offset voltage.

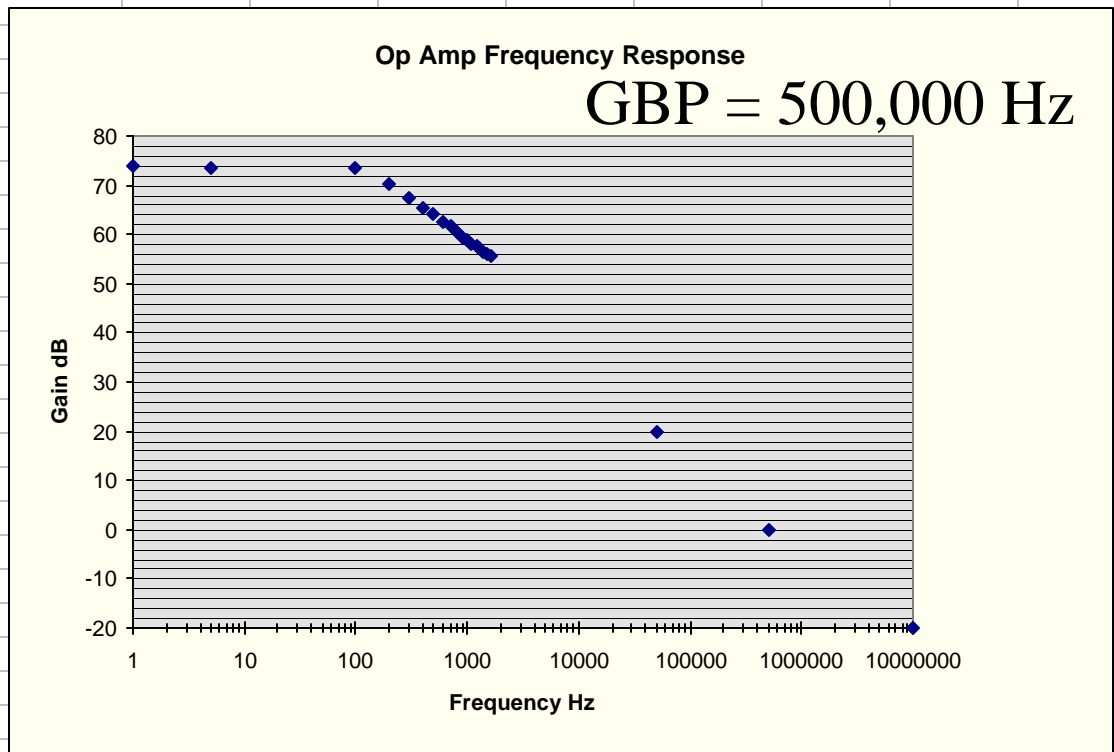
## AC TEST RESULTS

ROCHESTER INSTITUTE OF TECHNOLOGY  
MICROELECTRONIC ENGINEERING

LFF OPAMP.XLS FILE3B

LOT F960319 OPAMP TEST RESULTS - 1-29-97

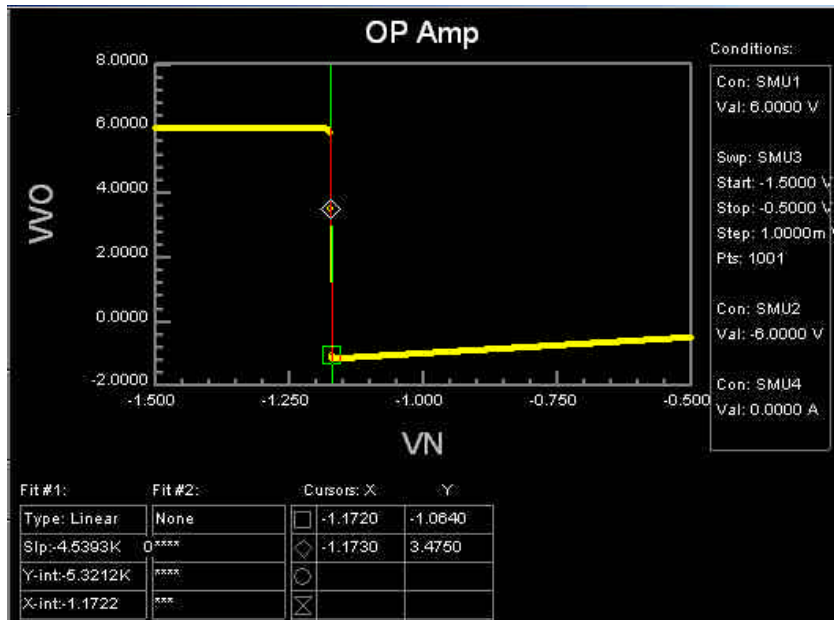
Frequency	Gain	Vout	Vin
hZ	dB	V	mV
1	73.9794	10	2
5	73.53387	9.5	2
100	73.33036	9.28	2
200	70.31748	6.56	2
300	67.53154	4.76	2
400	65.48316	3.76	2
500	63.97314	3.16	2
600	62.41148	2.64	2
700	61.51094	2.38	2
800	60.34067	2.08	2
900	59.46256	1.88	2
1000	58.68997	1.72	2
1100	58.0618	1.6	2
1200	57.50123	1.5	2
1300	57.14665	1.44	2
1400	56.5215	1.34	2
1500	56.1236	1.28	2
1600	55.56303	1.2	2
50000	20	0.02	2
500000	0	0.002	2
1000000	-20	0.0002	2



Rochester Institute of Technology  
Microelectronic Engineering

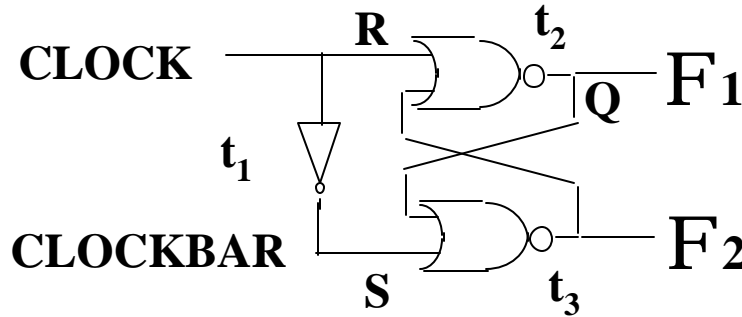
**CMOS OPERATIONAL AMPLIFIER**

**SUB-CMOS Process**

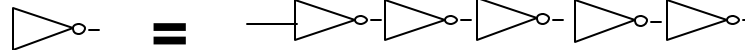
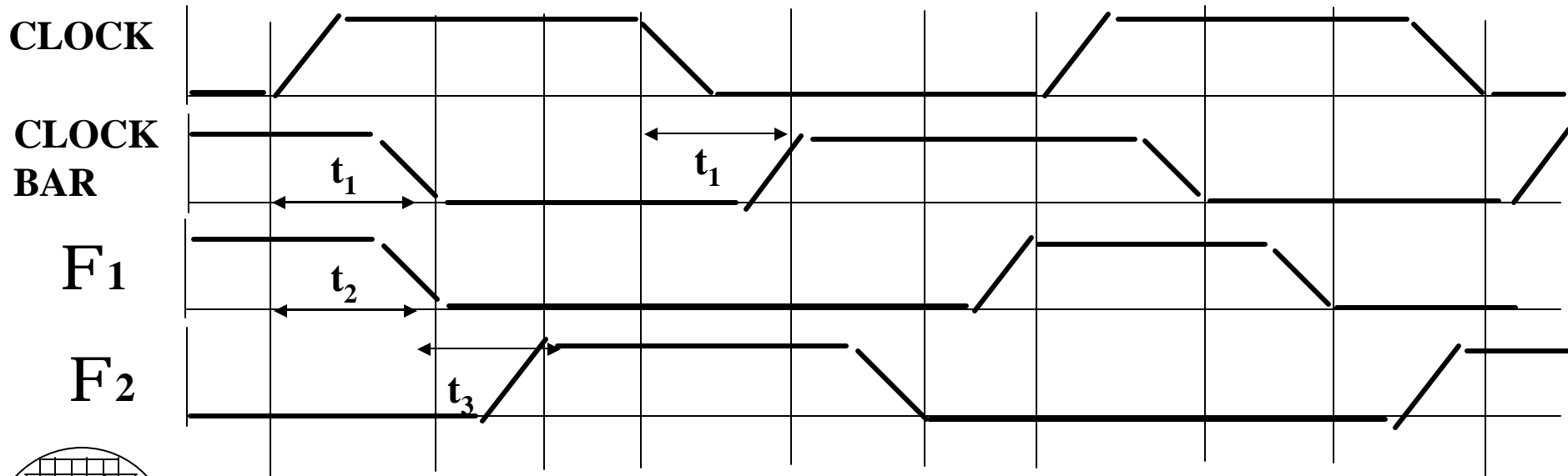


# TWO-PHASE CLOCK GENERATORS

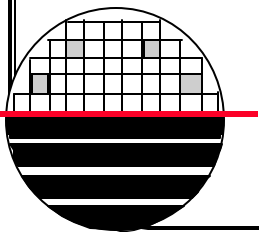
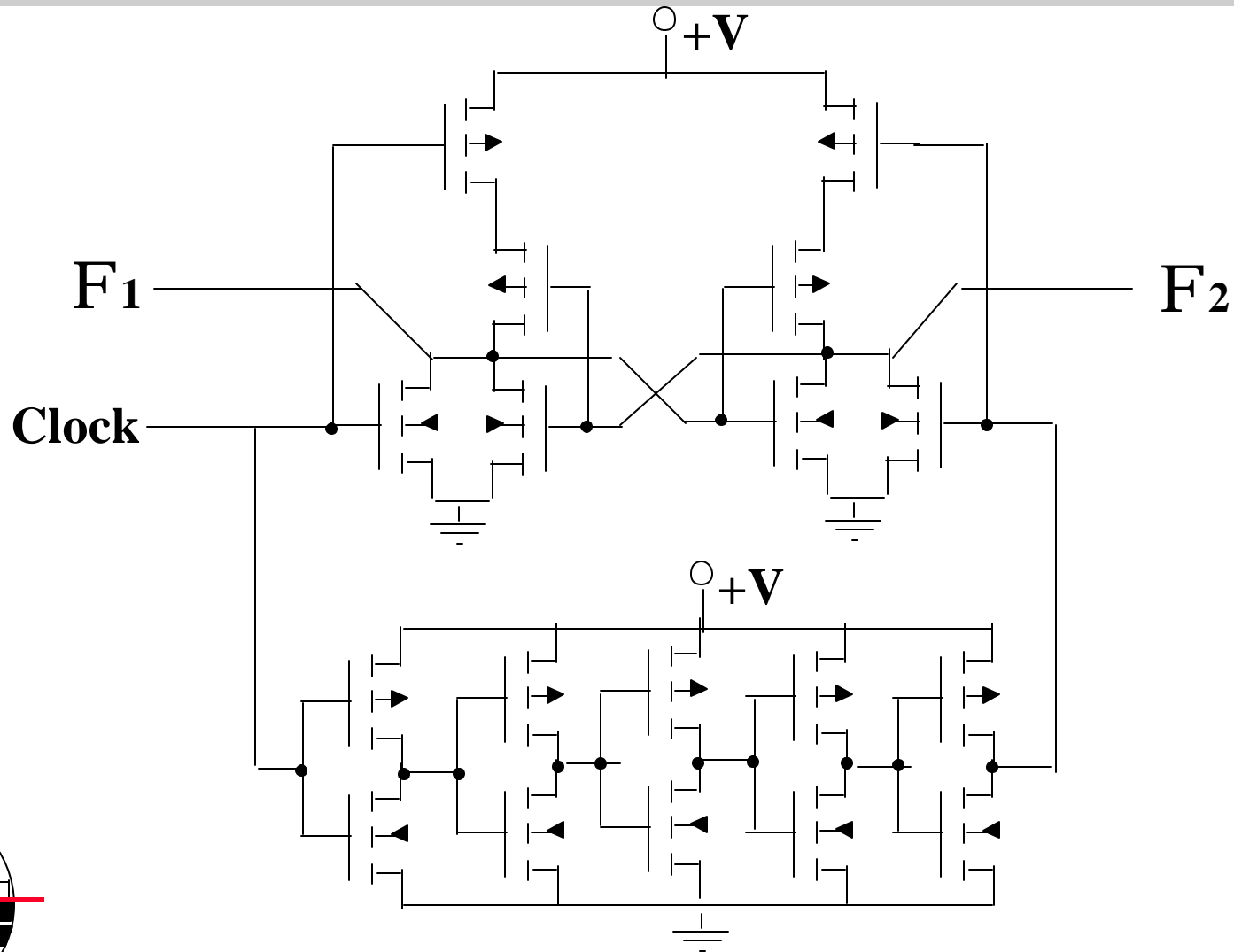
A	B	C
0	0	1
0	1	0
1	0	0
1	1	0



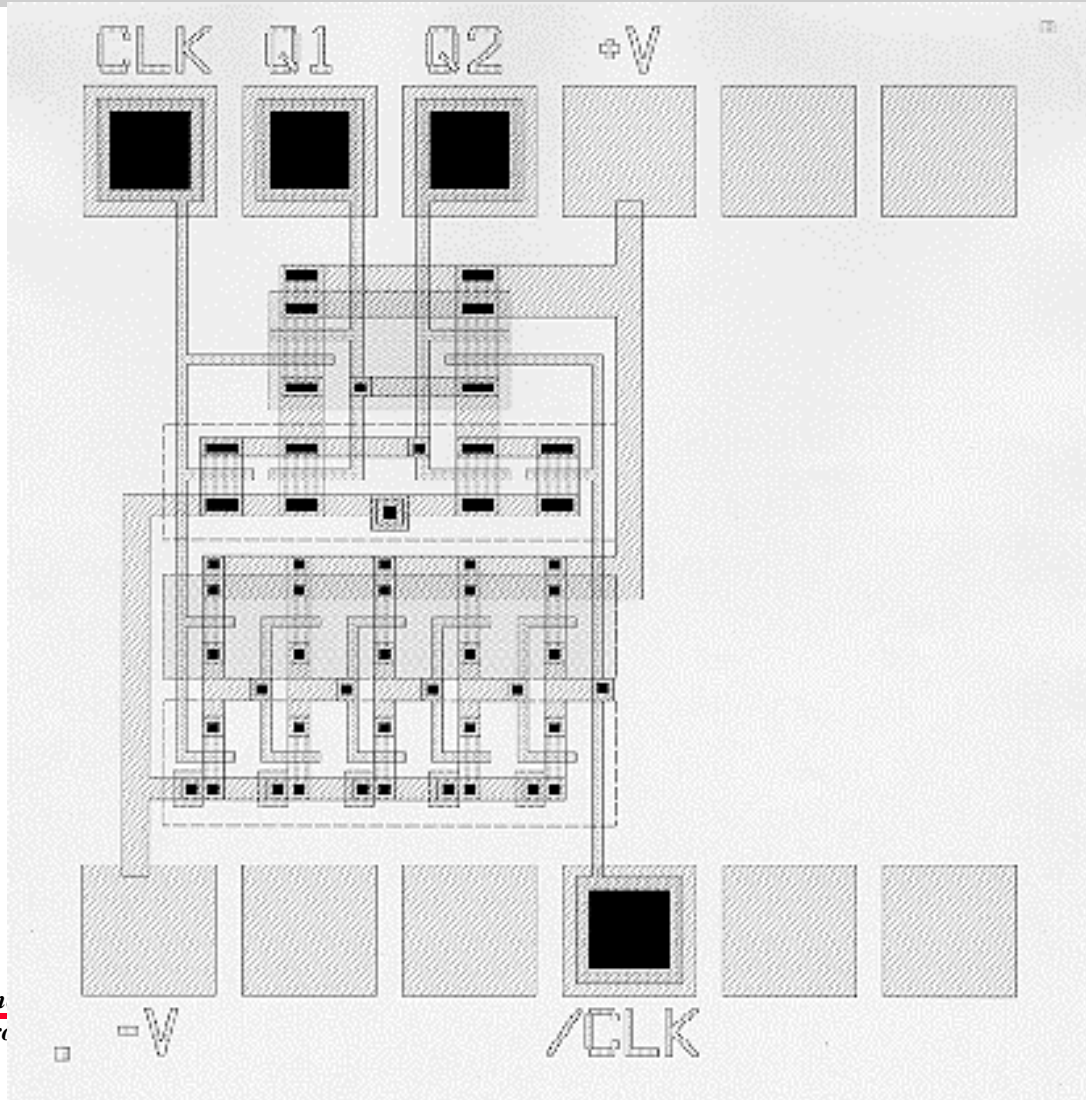
R	S	Q
0	0	Q <sub>n-1</sub>
0	1	1
1	0	0
1	1	INDETERMINATE



***TRANSISTOR LEVEL SCHEMATIC OF 2 PHASE CLOCK***

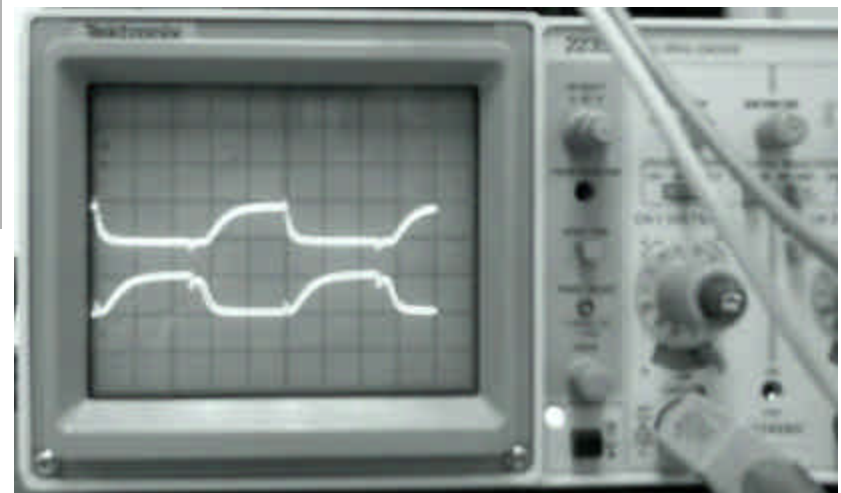
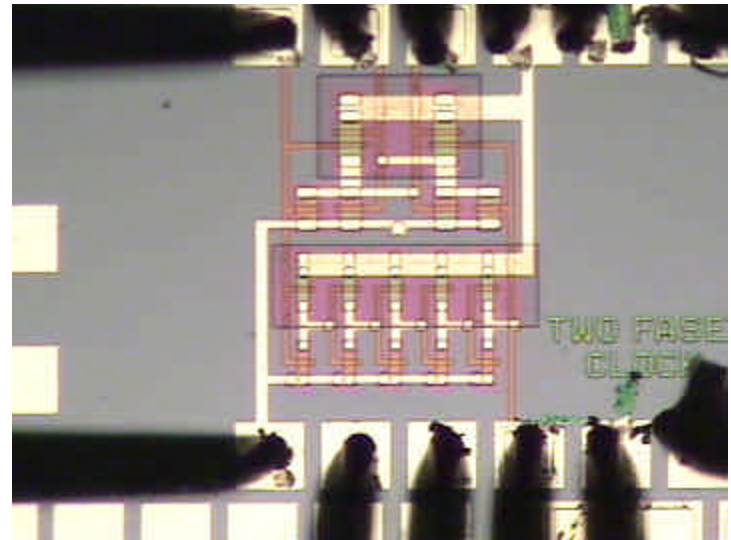
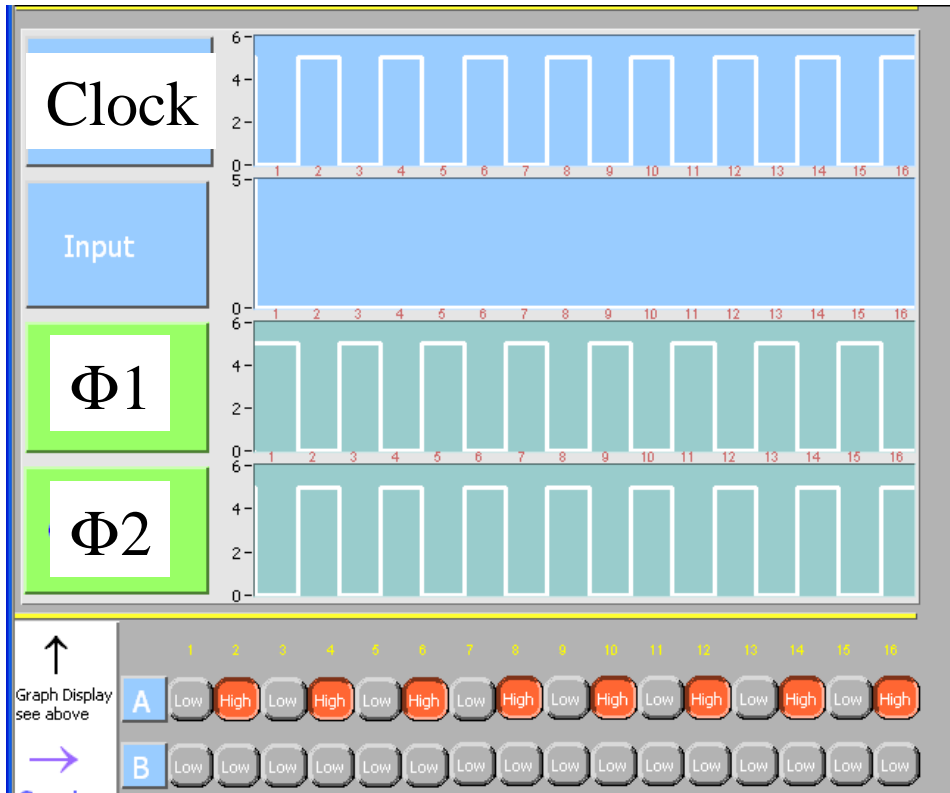


*LAYOUT OF TWO PHASE CLOCK*

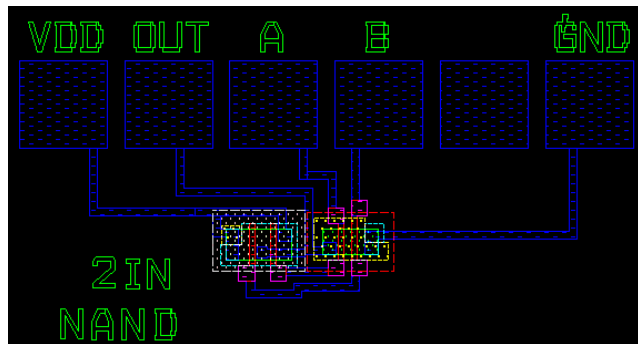
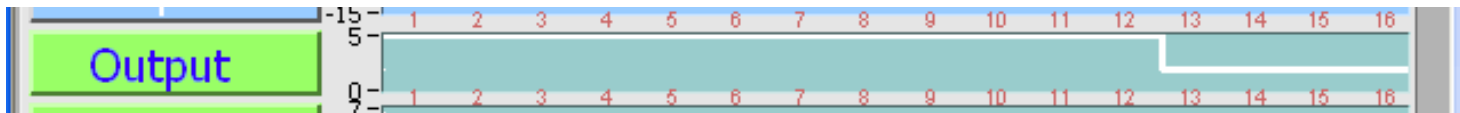


*Roch  
Micro*

**TWO PHASE NON OVERLAPPING CLOCK**



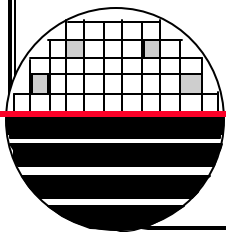
**CMOS 2 INPUT NAND**



Graph Display see above

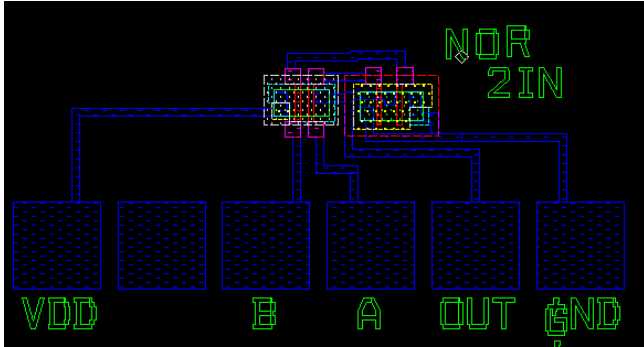
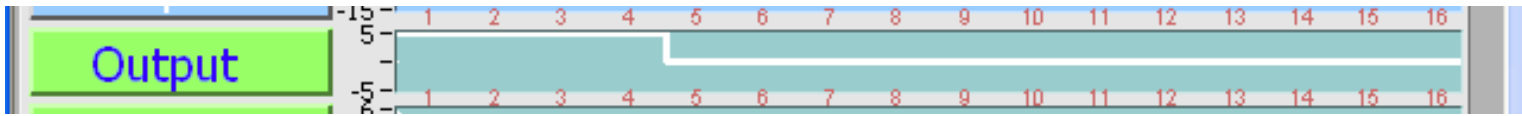
Setting the input terminals of the IUT

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
<b>A</b>	Low	Low	Low	Low	High	High	High	High	Low	Low	Low	Low	High	High	High	High
<b>B</b>	Low	Low	Low	Low	Low	Low	Low	Low	High	High	High	High	High	High	High	High
<b>C</b>	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low





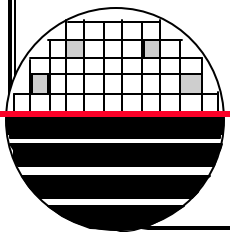
# CMOS 2-INPUT NOR



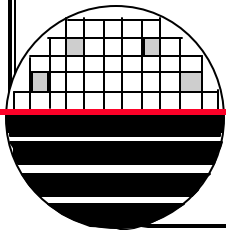
↑  
Graph Display  
see above

Setting  
the input  
terminals  
of the IUT

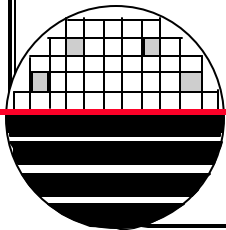
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
<b>A</b>	Low	Low	Low	Low	High	High	High	High	Low	Low	Low	Low	High	High	High	High
<b>B</b>	Low	Low	Low	Low	Low	Low	Low	Low	High	High	High	High	High	High	High	High
<b>C</b>	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low	Low



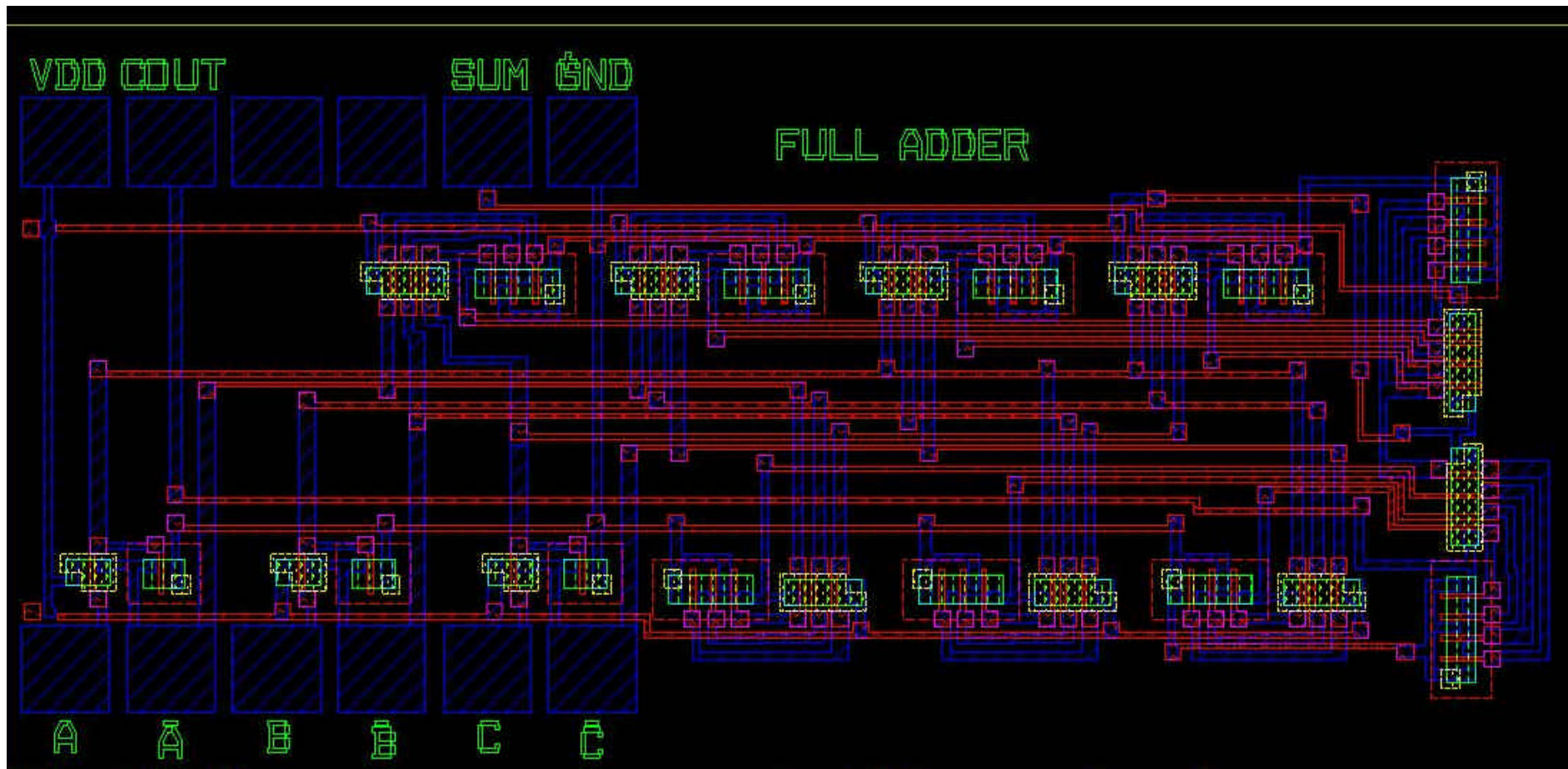
*CMOS 3-INPUT NAND*



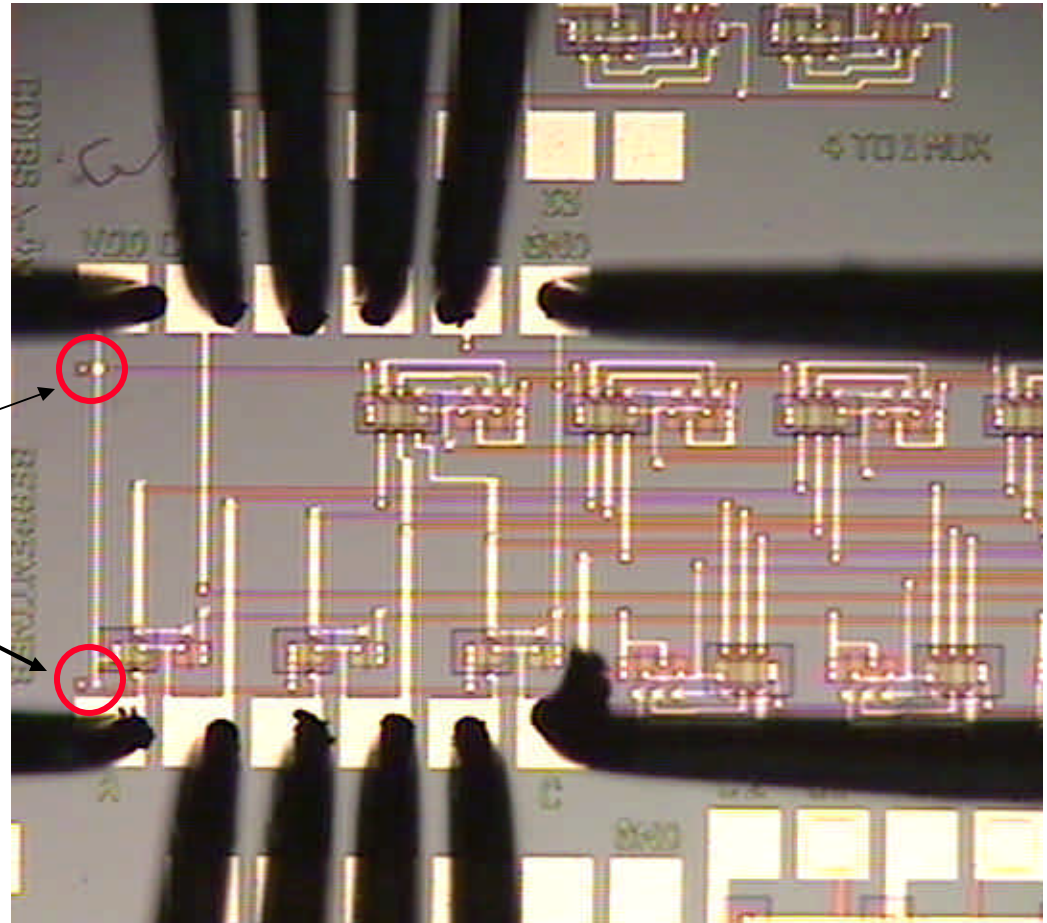
*CMOS 3-INPUT NOR*



*FULL ADDER DESIGN*

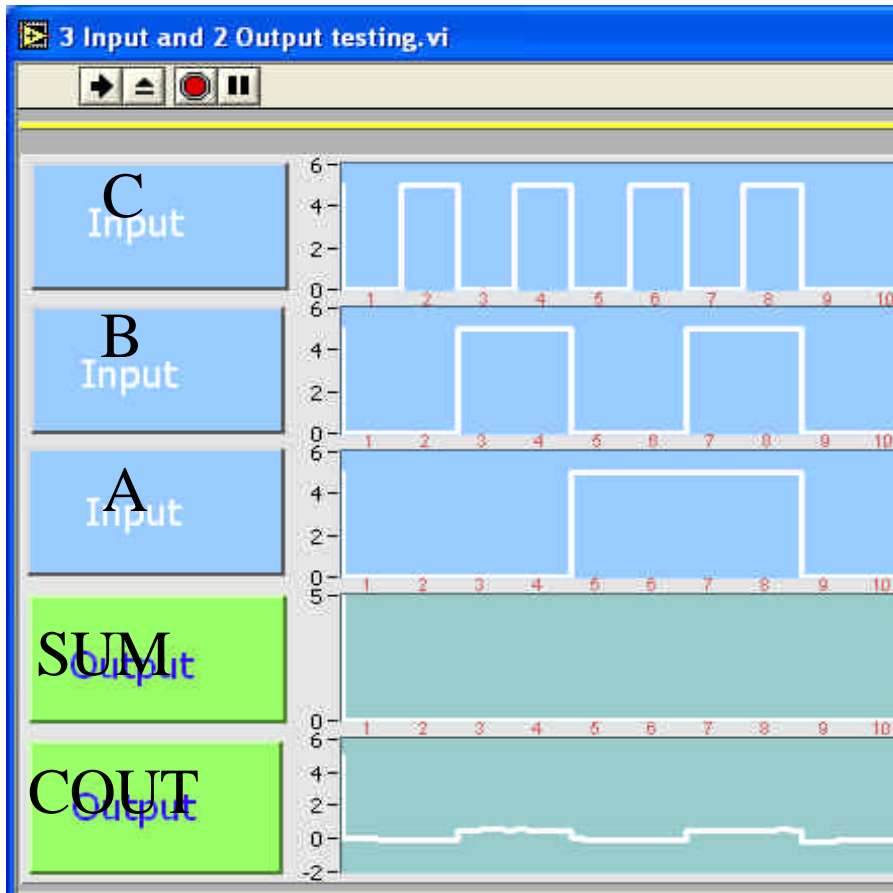


***FULL ADDER BROKEN VDD CONNECTION***



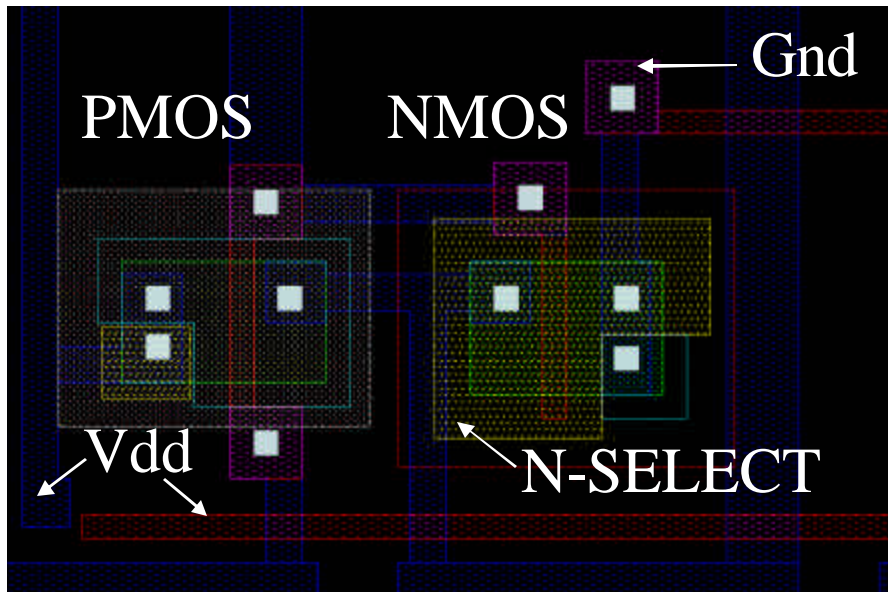
Broken Vdd Connections

***FULL ADDER TEST RESULTS***

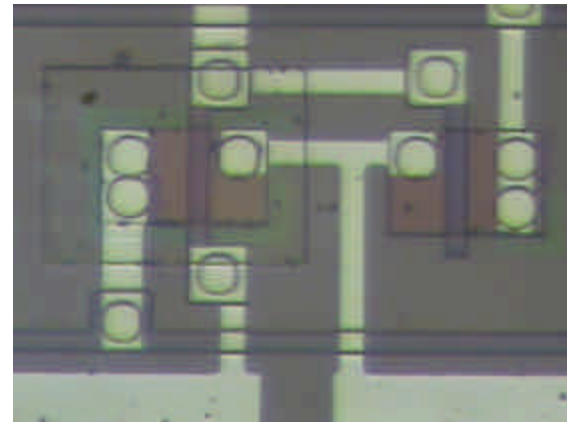
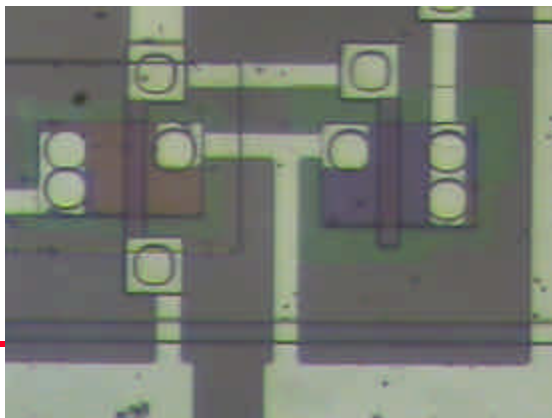
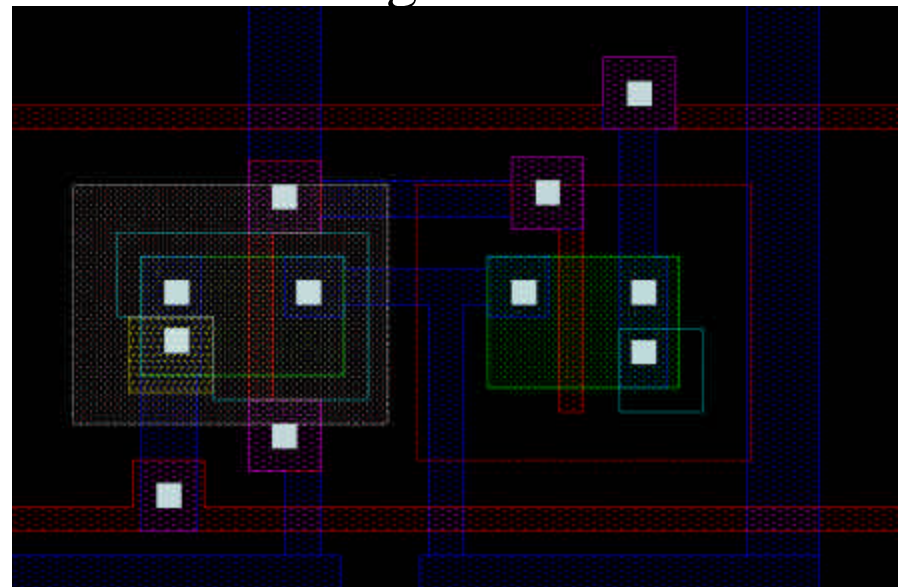


***FULL ADDER MISSING N-SELECT ON SOME INVERTERS***

Vdd Connection Broken

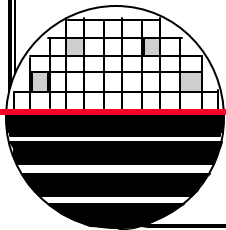


Missing N-Select



## *DISCUSSION ON N-SELECT AND P-SELECT*

The designer needs only one of n-select or p-select to make the masks needed for CMOS. The design rule checkers can also be made to work with only one of the two select layers. At RIT we use both n-select and p-select in the design to make the design rule checks easier to implement. Thus at RIT both should be available for making the masks. On the next page you find that both n-select and p-select are used in making the masks for the sub-micron CMOS process. On the following page you see that only p-select is used to make the masks. It does not matter how it is done but it has to be done correctly.

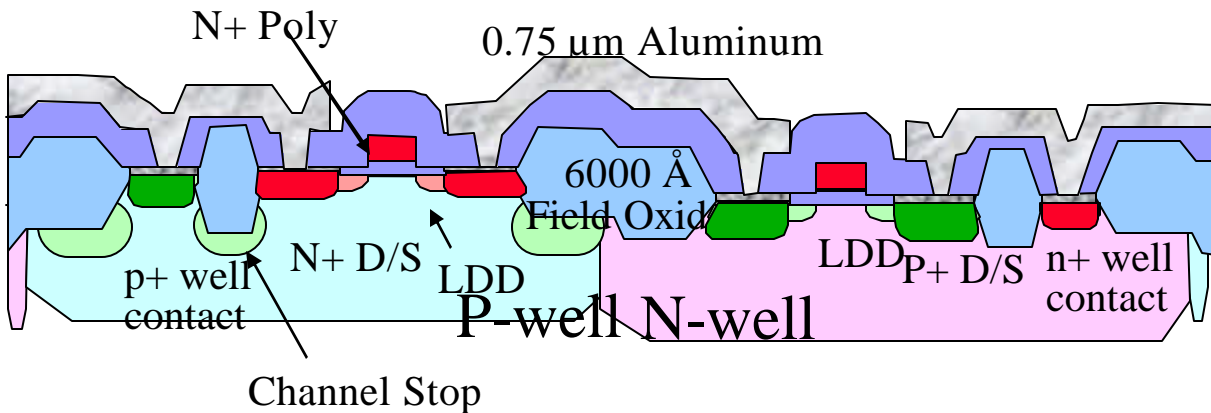




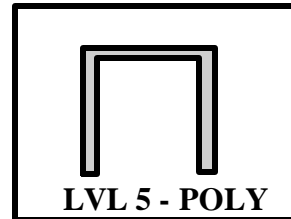
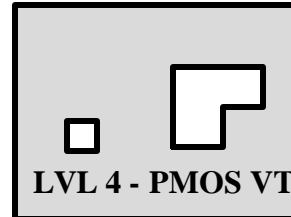
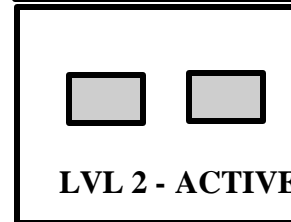
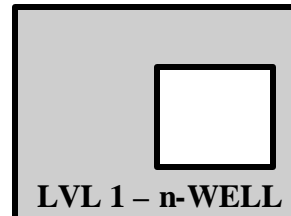
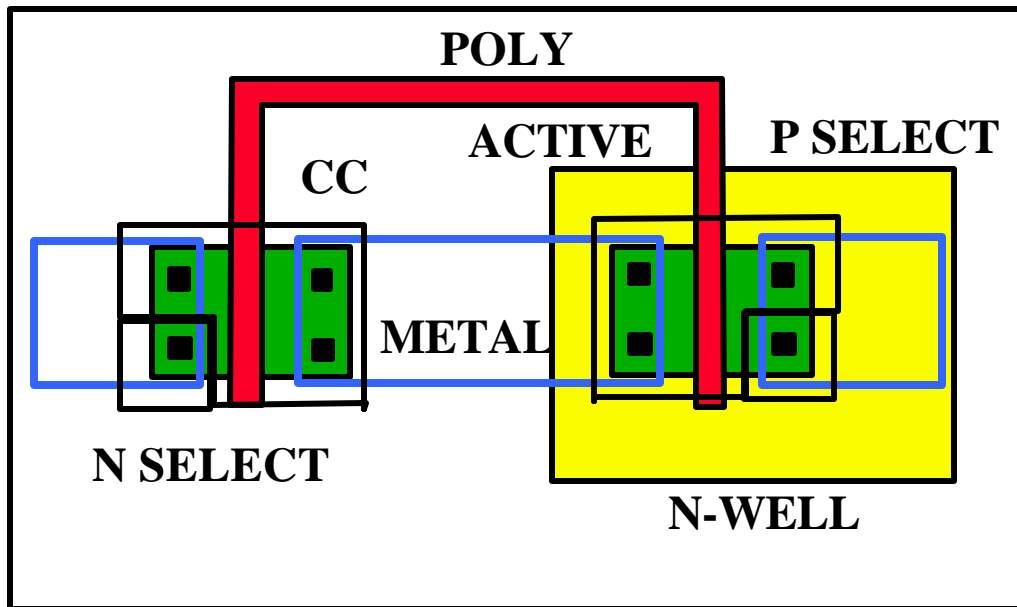
# RIT SUB-CMOS PROCESS

NMOSFET

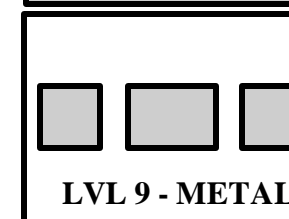
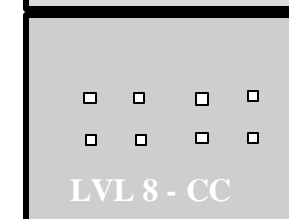
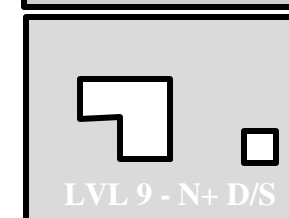
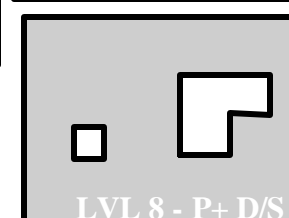
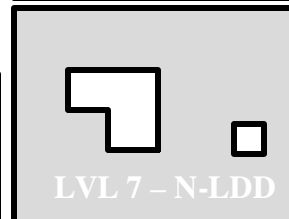
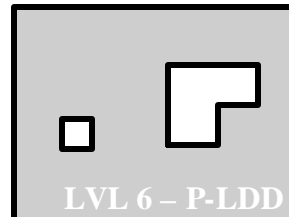
PMOSFET



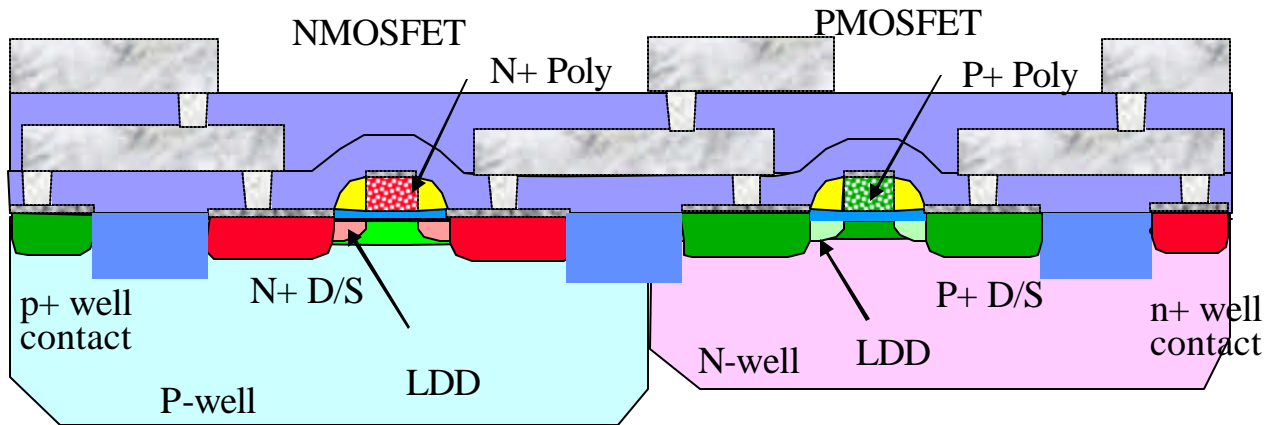
N-type Substrate 10 ohm-cm



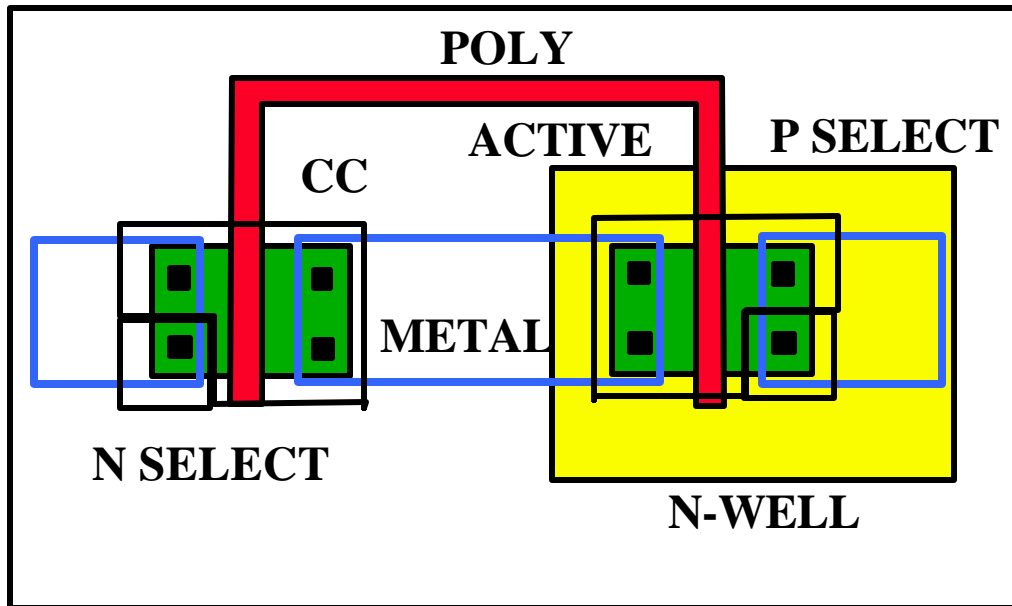
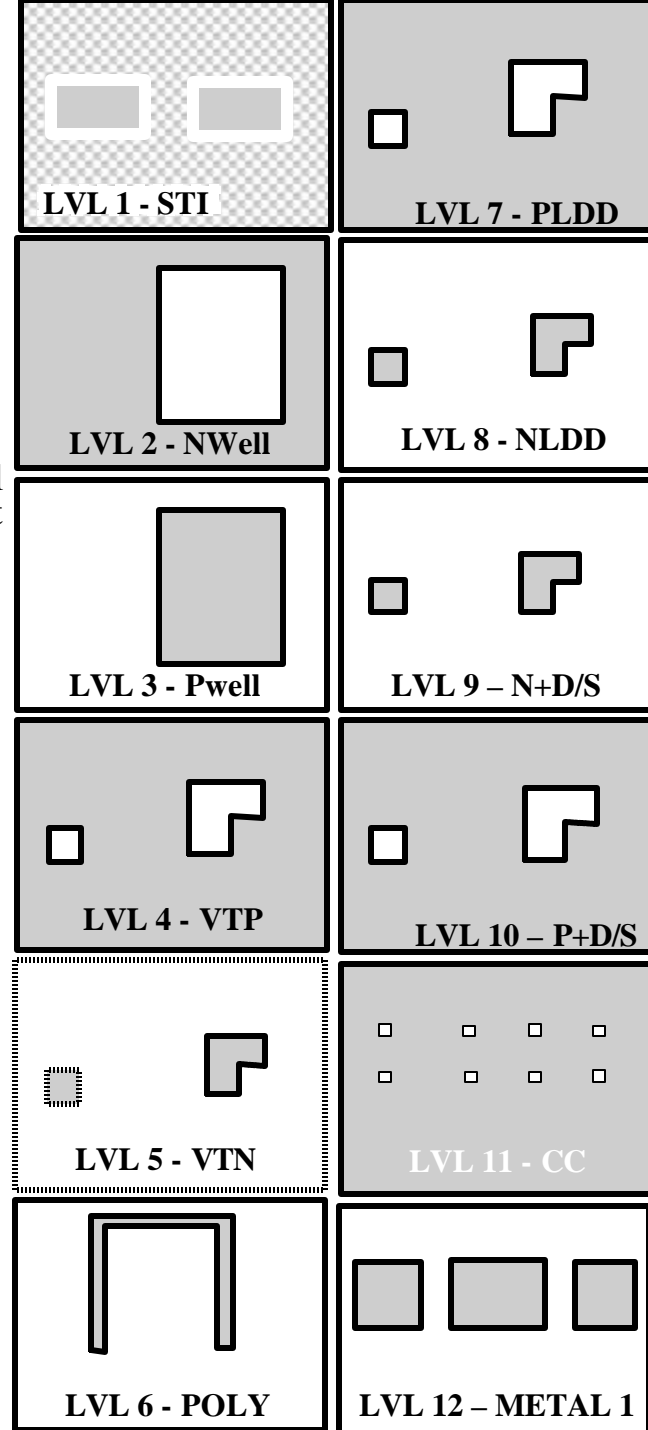
11 PHOTO LEVELS



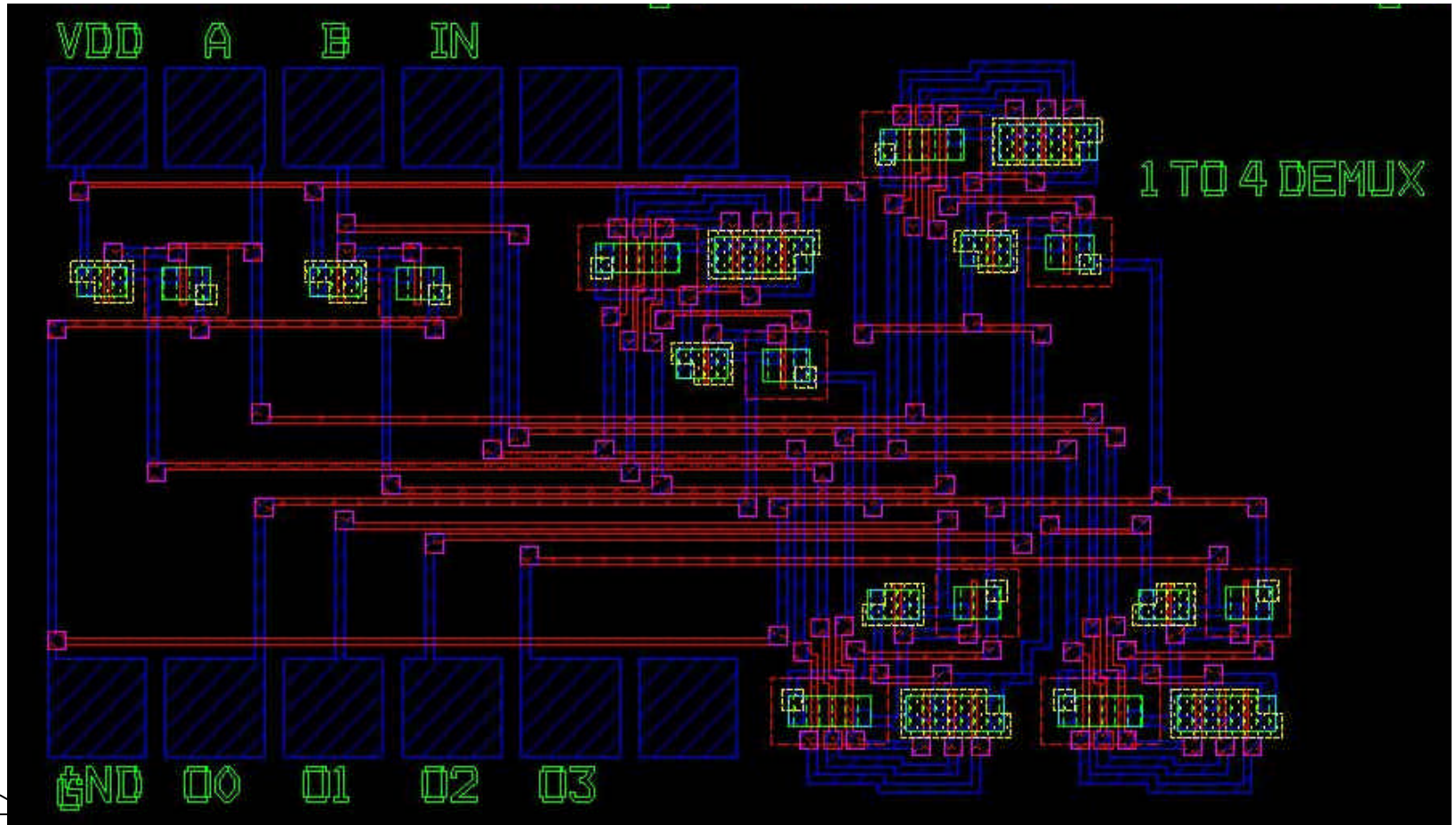
# RIT ADVANCED CMOS PROCESS



## 12 PHOTO LEVELS

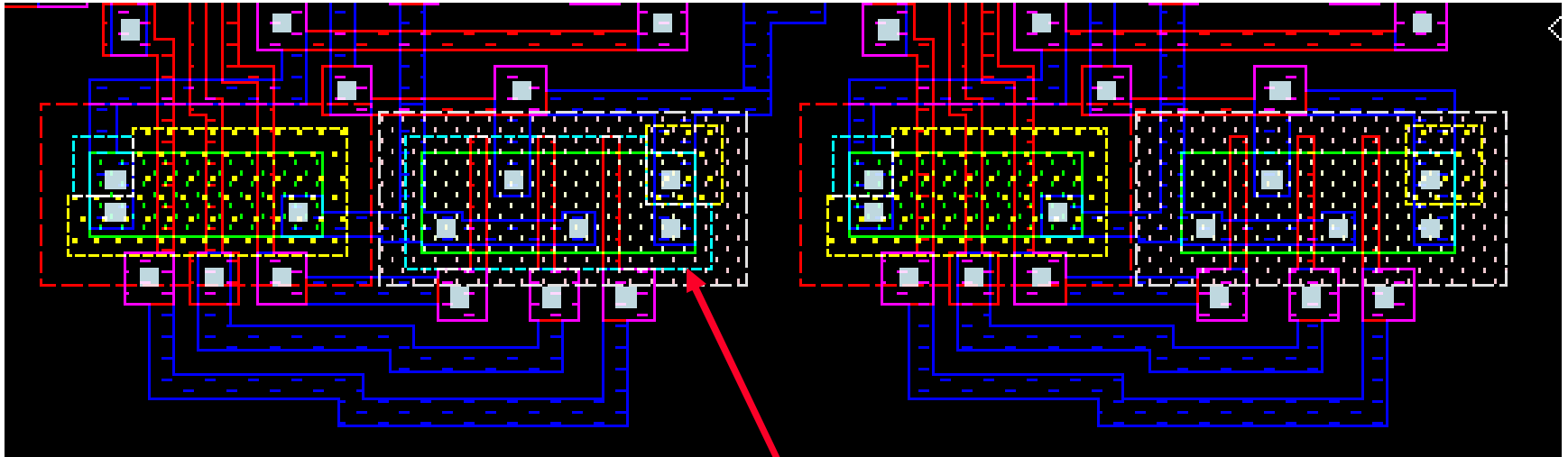


# 1 TO 4 DEMUX DESIGN

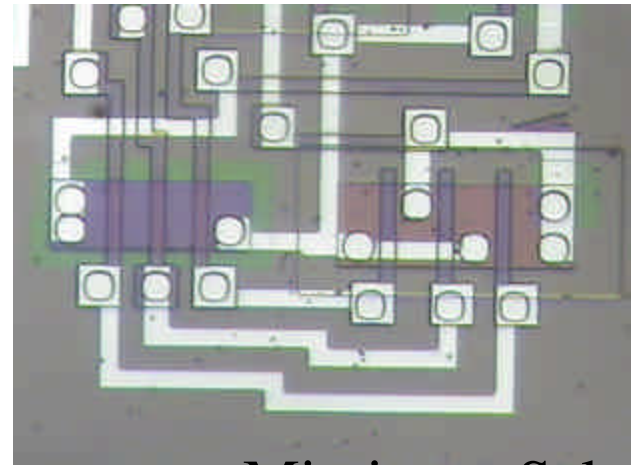
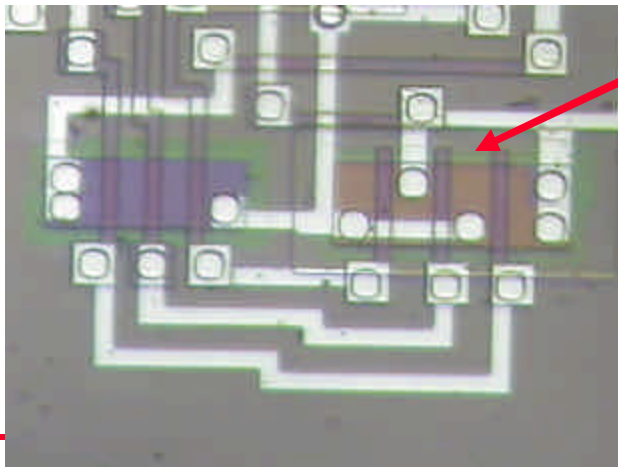


Rochester Institute of Technology  
Microelectronic Engineering

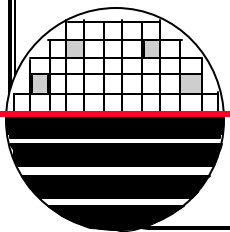
***MISSING P-SELECT ON SOME NOR GATES***



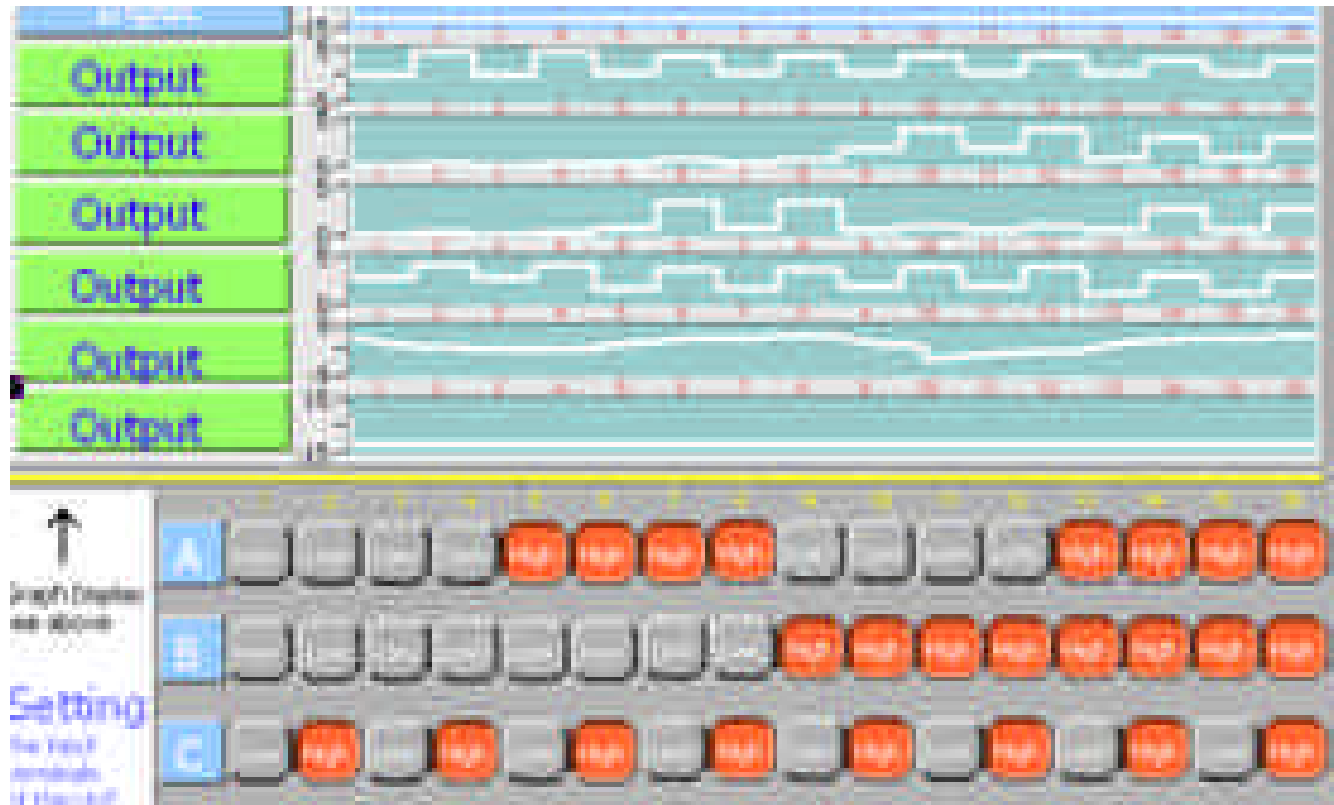
P-Select



Missing p-Select



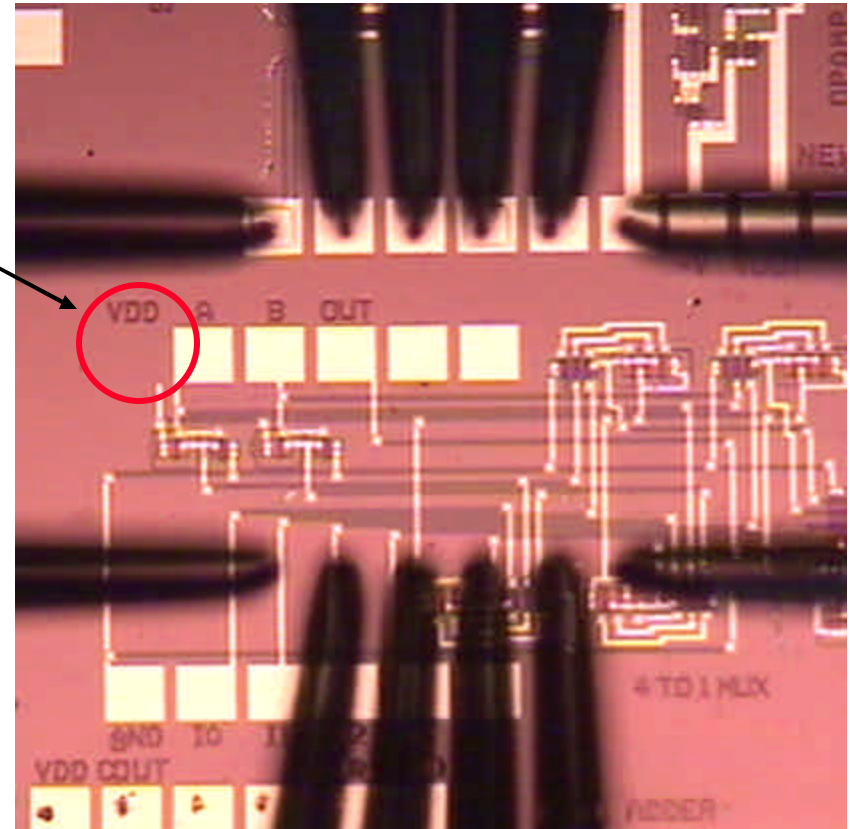
# 1 TO 4 DEMUX TEST RESULTS



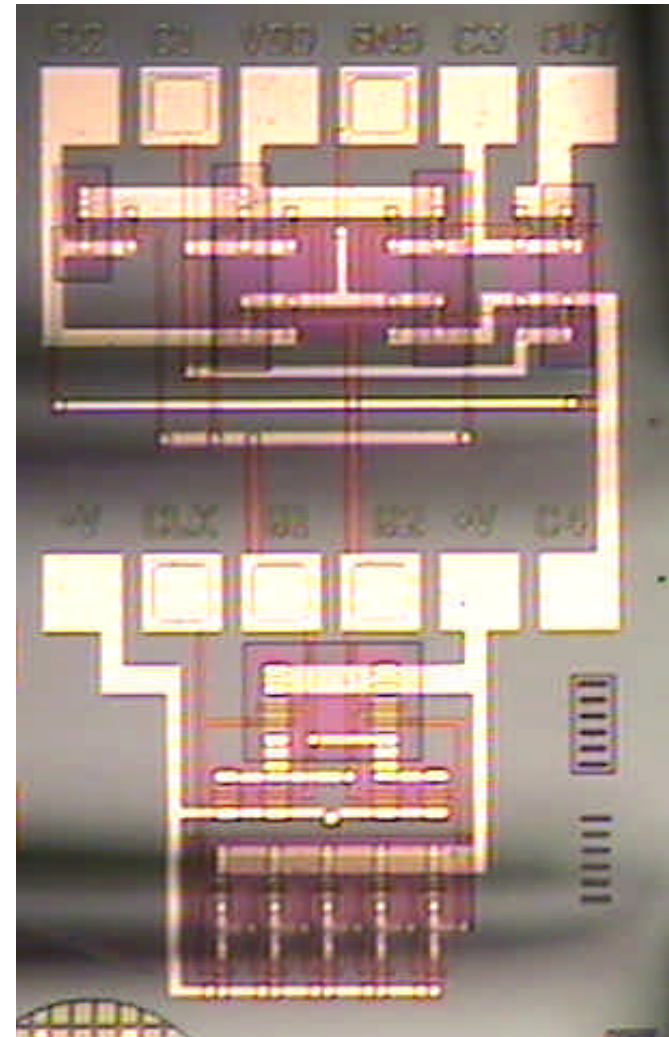
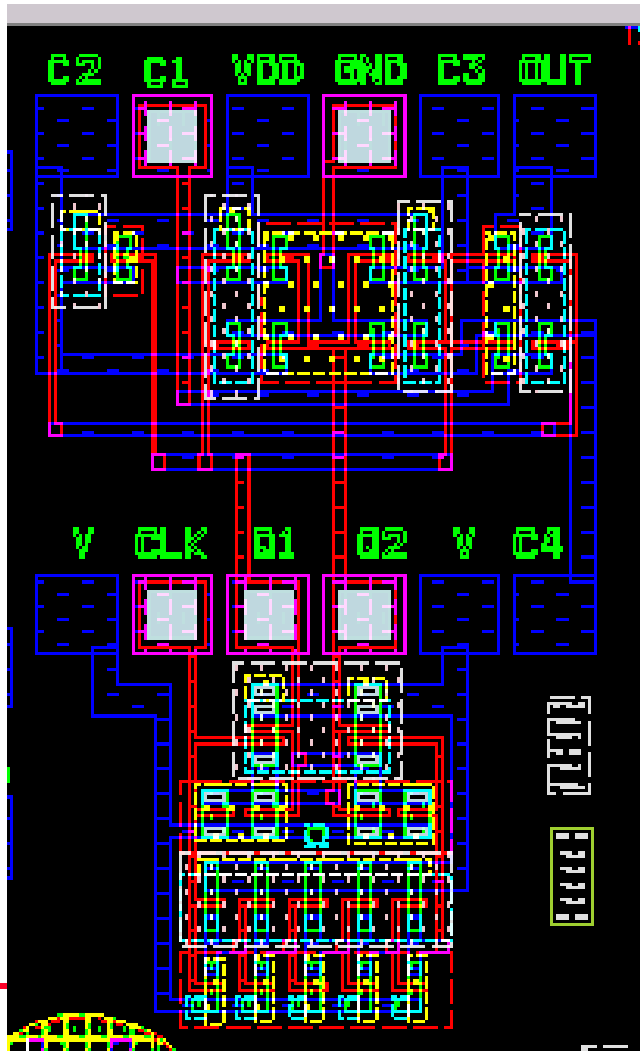
Missing p-Select on some 3-NORs

*4 to 1 MUX*

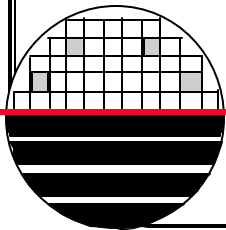
Missing Vdd Pad



*VOLTAGE DOUBLER*



***VOLTAGE DOUBLER TEST RESULTS***





REFERENCES

